505799696 12/03/2019

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shunpei Yamazaki	11/08/2019

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.
Street Address:	398, HASE
City:	ATSUGI-SHI, KANAGAWA-KEN
State/Country:	JAPAN
Postal Code:	243-0036

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16618831

CORRESPONDENCE DATA

Fax Number: (877)769-7945

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (202) 783-5070 **Email:** apsi@fr.com

Correspondent Name: JOHN F. HAYDEN

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Address Line 2: P.O.BOX 1022

Address Line 4: MINNEAPOLIS, MINNESOTA 55440-1022

ATTORNEY DOCKET NUMBER:	12732-1981US1
NAME OF SUBMITTER:	APRIL K. SAUNDERS-FULLER
SIGNATURE:	/April K. Saunders-Fuller/
DATE SIGNED:	12/03/2019

Total Attachments: 1

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PATENT REEL: 051159 FRAME: 0378

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Attorney Docket No. 12732-1981US1 Client Reference No. PCTUS26728

ASSIGNMENT

For valuable consideration, I, <u>Shunpei YAMAZAKI of Setagaya</u>, <u>Tokyo, Japan</u> hereby assign to <u>Semiconductor Energy Laboratory Co., Ltd.</u>, a <u>Japanese</u> corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and
interest throughout the world in the inventions and improvements which are subject of an application for
United States Patent signed by me this day, entitled SEMICONDUCTOR DEVICE, AND METHOD OF
MANUFACTURING THE SEMICONDUCTOR DEVICE, filed December 3, 2019, and assigned
U.S. Serial Number 16/618,831 , and I authorize and request the Assignee or the attorneys
appointed in said application to hereafter complete this assignment by inserting above the filing date and
serial number of said application when known; this assignment including said application, any and all United
States and foreign patents, utility models, and design registrations granted for any of said inventions or
improvements, and the right to claim priority based on the filing date of said application under the
International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the
European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in
all countries in my name or in its own name for patents, utility models, design registrations and like rights of
exclusion and for inventors' certificates for said inventions and improvements; and I agree for myself and
my respective heirs, legal representatives and assigns, without further compensation to perform such lawful
acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents
as the Assignee may reasonably request to effectuate fully this assignment.

Signature

RECORDED: 12/03/2019

Name:

Shunpei VAMAZAKI

Date:

11/08/2019

PATENT REEL: 051159 FRAME: 0379